

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming Sun</td> <td>01/28/2011</td> </tr> <tr> <td>Yueh Se Ho</td> <td>01/24/2011</td> </tr> </tbody> </table>		Name	Execution Date	Ming Sun	01/28/2011	Yueh Se Ho	01/24/2011
Name	Execution Date						
Ming Sun	01/28/2011						
Yueh Se Ho	01/24/2011						
RECEIVING PARTY DATA							
Name:	Alpha and Omega Semiconductor Incorporated						
Street Address:	475 Oakmead Pkwy						
City:	Sunnyvale						
State/Country:	CALIFORNIA						
Postal Code:	94085						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13454342</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13454342		
Property Type	Number						
Application Number:	13454342						
CORRESPONDENCE DATA							
Fax Number:	(650)949-4118						
Email:	boinlin@gmail.com						
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>							
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Address Line 4:	Los Altos Hills, CALIFORNIA 94022						
ATTORNEY DOCKET NUMBER:	AOS-0505C						
NAME OF SUBMITTER:	Bo-In Lin						
Total Attachments: 2 source=AOS0505D Signatures#page1.tif source=AOS0505D Signatures#page2.tif							

CH \$40.00 13454342

ASSIGNMENT

INVENTOR AND CITY Whereas, I, **Yueh Se Ho** of 735 Iris Avenue, Sunnyvale, California 94086

have invented:

TITLE: PACKAGING CONFIGURATIONS FOR VERTICAL ELECTRONIC DEVICES USING CONDUCTIVE TRACES DISPOSED ON LAMINATED BOARD LAYERS

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor on 24th Jan, 2010;

Whereas, **Alpha and Omega Semiconductor Incorporated**, a California Company, having its registered address at 475 Oakmead Pkwy, Sunnyvale, CA 94085, USA, (hereinafter called **AOS**), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to **AOS**, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to **AOS** its successors and assigns; and I hereby agree that **AOS** may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND Signed and Sealed at Sunnyvale, California

DATE on 24th Jan, 2010.



SIGNATURE OF INVENTOR

ASSIGNMENT

INVENTOR AND CITY Whereas, I, **Ming Sun** of 1222 Pennyroyal Terrace Sunnyvale, California 94087

have invented:

TITLE: PACKAGING CONFIGURATIONS FOR VERTICAL ELECTRONIC DEVICES USING CONDUCTIVE TRACES DISPOSED ON LAMINATED BOARD LAYERS

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor on 1/28, 2011;

Whereas, **Alpha and Omega Semiconductor Incorporated**, a California Company, having its registered address at 475 Oakmead Pkwy, Sunnyvale, CA 94085, USA, (hereinafter called **AOS**), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to **AOS**, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to **AOS** its successors and assigns; and I hereby agree that **AOS** may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND Signed and Sealed at Sunnyvale, California

DATE on 1/28, 2011.


SIGNATURE OF INVENTOR